

Electronic Patent Application Fee Transmittal				
Application Number:	10598124			
Filing Date:	18-Aug-2006			
Title of Invention:	Solder composition and method of bump formation therewith			
First Named Inventor/Applicant Name:	Isao Sakamoto			
Filer:	Sean Christophe Myers-Payne/Sonja Combest			
Attorney Docket Number:	P30245			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810